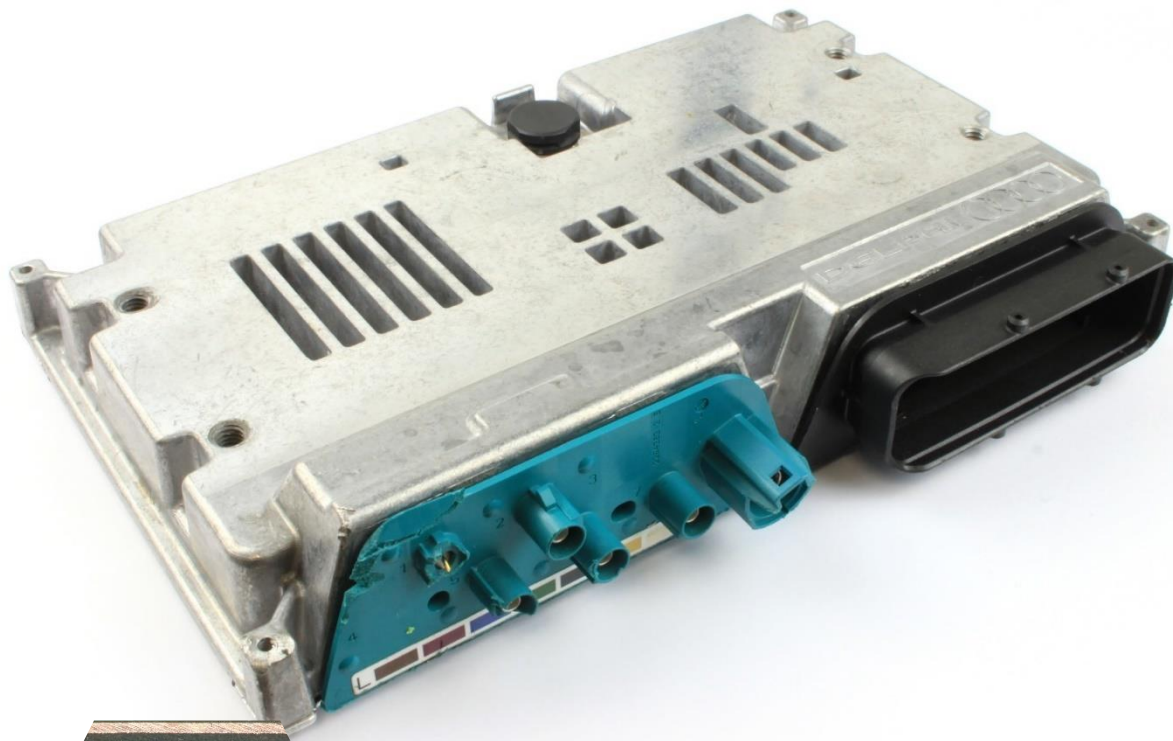




Audi A8 zFAS Advanced Driver Assistance System Platform Aptiv (Delphi) 4N0.907.107

SP19502 - report by David Le Gac
December 2019 – Sample

SAMPLE

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Block Diagram

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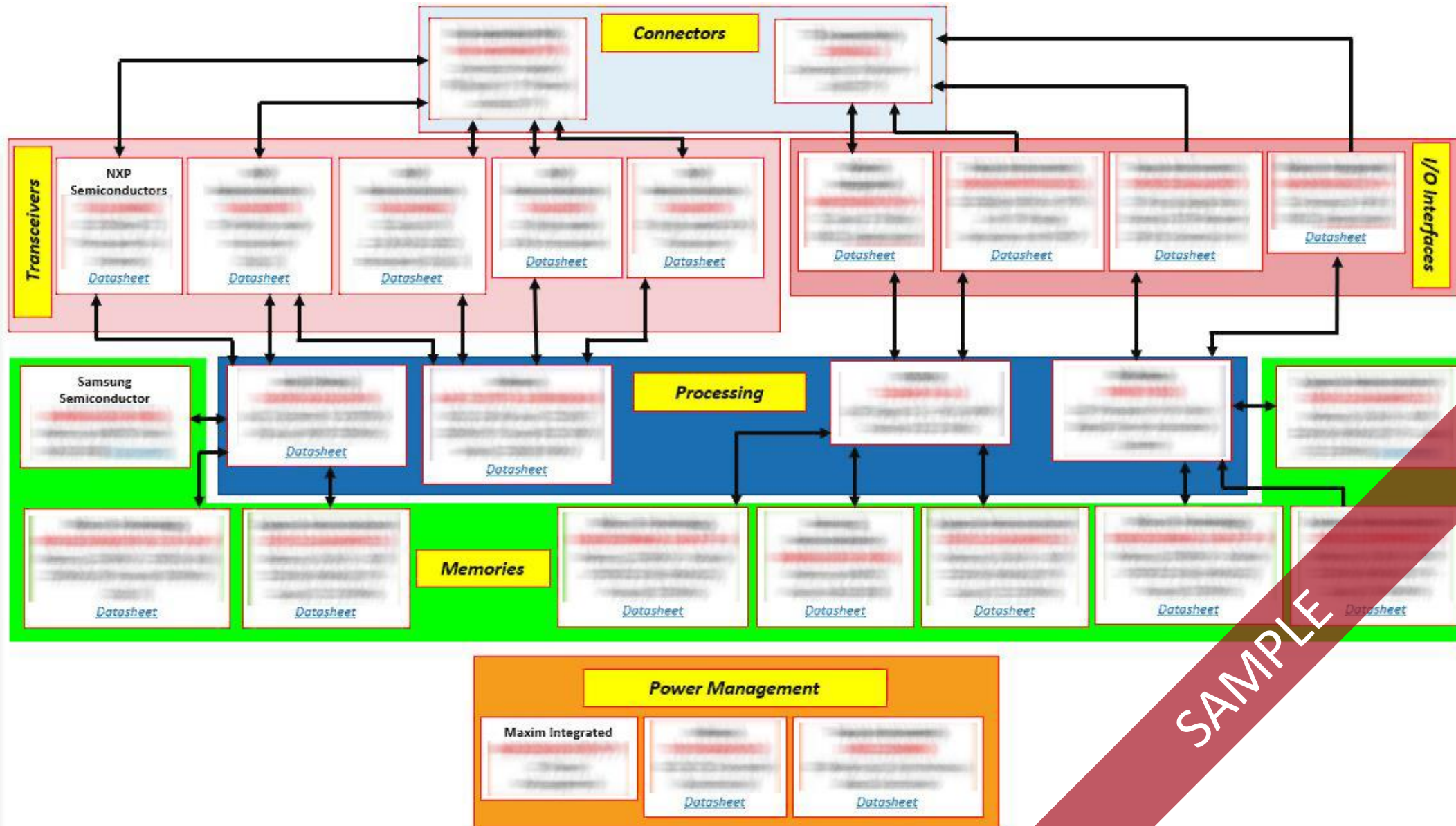
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Reverse Costing Methodology

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The reverse costing analysis is conducted in several phases:

- **The initialization of the analysis**

Pictures of the elements to be studied.

Identification of the components.

- **Description of the material in the “SYScost+” software**

Creation of an “estimation project” of the studied board with SYScost+ software.

Construction of the Bill of Material (BOM).

- **Assessing the material**

Searching for the price of each reference among distributors and manufacturers.

Assessing the cost of the PCB and of the unaccounted references (unknown by distributors)

The BOM is valued with SYScost+ : price simulation according to the requested quantities.

- **Assessing the assembling and test phases**

Assembly and test lines are modeled with the SYScost+ software.

The assembly and tests costs are estimated.

- **Production cost & manufacturer price**

Estimation of the production cost & manufacturer price.

- **Report**

A report is edited.

SYS.cost+©, is a software tool developed by SYSTEM PLUS CONSULTING to calculate the cost of electronic boards. More information on the software can be found at www.systemplus.fr.

Global Views

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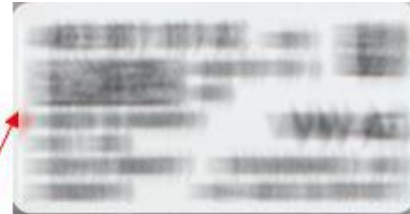
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Total Weight :  g



Information about the manufacturing country : 

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Global views of the zFAS Control Unit.

Electronic Board – Top Side – Global View

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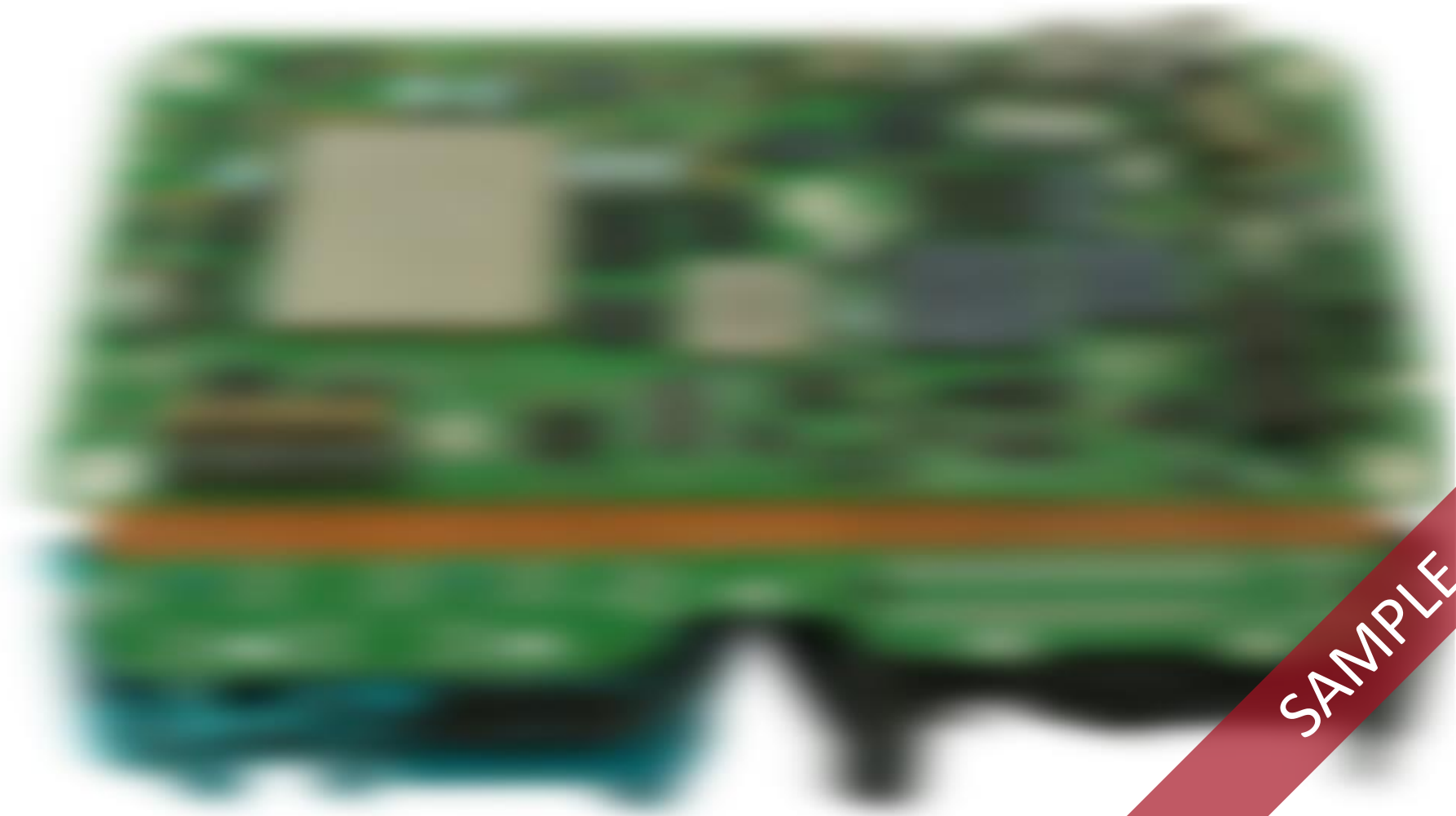
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PCB Characteristics :		
Material: FR4	Layers number: 8	Dimensions : 100mm x 100mm
Total Thickness: 1.6mm	External copper thickness: 35µm	Internal copper thickness: 18µm
Finishing : ENIG (Au/Ni/P)	Drilling holes number : 100	Drilling diameter : 0.3mm



Electronic Board – Top Side – Main Components Identification

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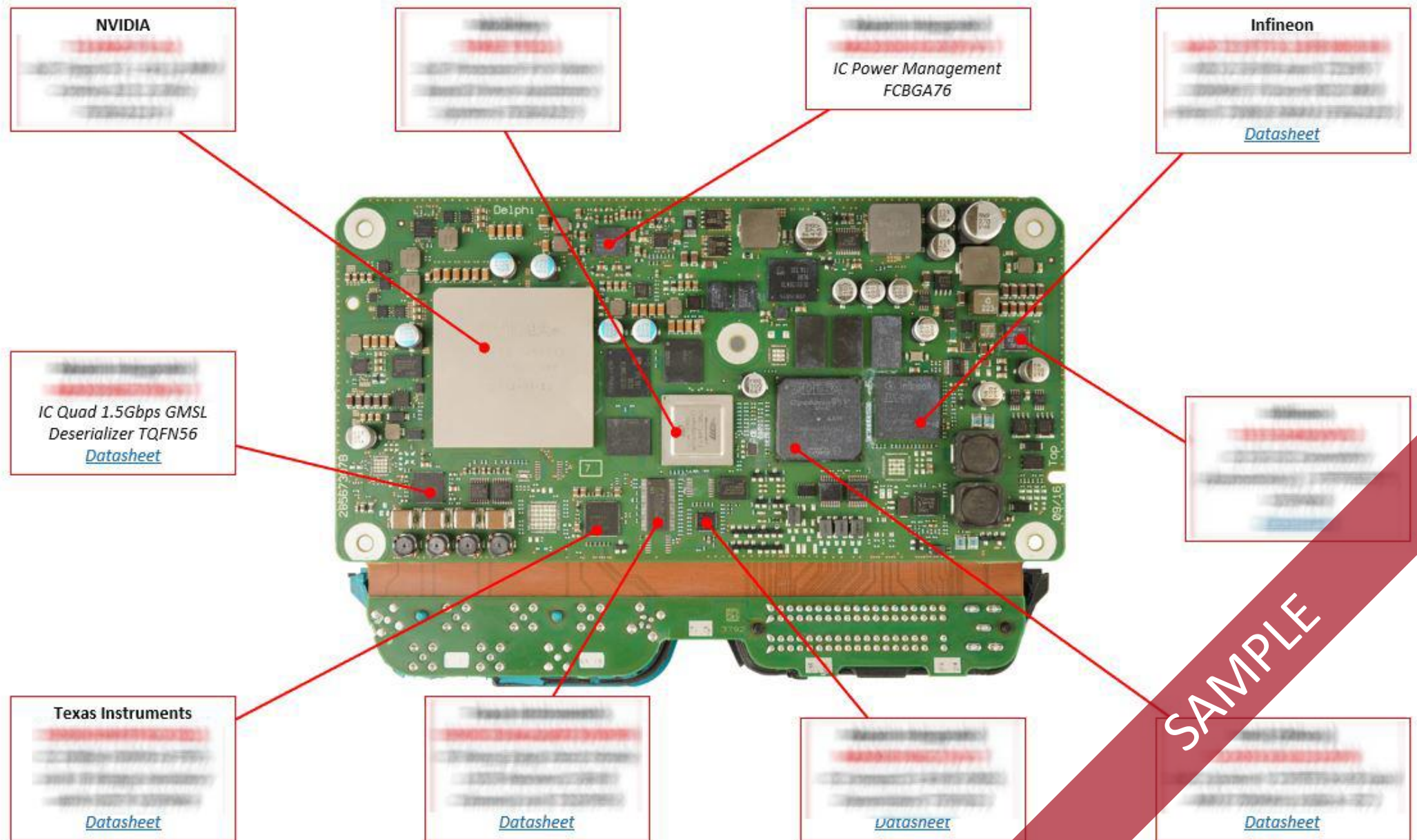
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NVIDIA T124XA-P1-A1 – Summary of the Physical Analysis

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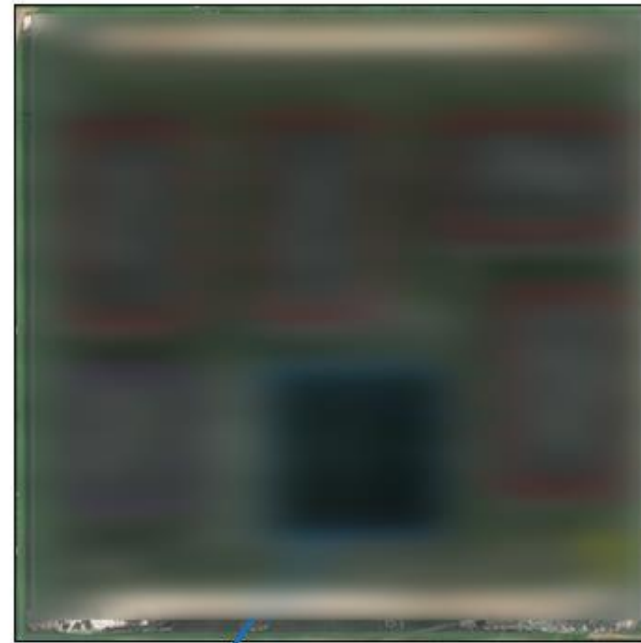
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Package Opening – Top View – Optical View
©2019 by System Plus Consulting



Graphics
Processing Unit
Die



VBU056
AEC-Q100 Grade 2



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PCB Cost – Electronic Board

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- Assessing the BOM
- ▶ **PCB Cost Estimation**
- ICs Cost Estimation
- BOM Cost – Electronics
- Housing Parts Estimation
- BOM Cost - Housing
- Material Cost Breakdown
- Added-Value Cost
- Manufacturing Cost

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Substrate Description			Process Description		
Stacked materials		Layers #	Product class		
			Mechanical Drilling & Milling		
			Total number of holes:		
			Minimal hole diameter:		
			Laser Drilling		
			Total number of holes:		
			Minimal hole diameter:		
Total number of conductor layers			HDI Class		
Finishing #1			Number of standard coupons		
Finishing #2			Number of specific coupons		
Panelization Description			Economical Description		
Panel	Length	Width	Area of manufacturing		
Panel size (mm)			Year	Quantity	Batch size
Panel area (dm2)					
Board			Material supply ing ratio:		
Board size (mm)			Material scrap ratio:		
Board area (dm2)			Manufacturing yield:		
Boards per panel			Manufacturing overheads:		

Electronic Board Characteristics
(interface of the costing tool **PCB Price+**).

Material costs		2019	
		Cost	
Material cost		\$	%
Copper foils		\$	%
Prepregs		\$	%
Laminates		\$	%
Others		\$	%
Finish #1		\$	%
Finish #2		\$	%
Supplying		\$	%
Scrap		\$	%
Total Material Costs		\$	%
Process costs		2019	
		Cost	
Process		\$	%
Drilling/Milling		\$	%
(of which: drilling bits)		\$	%
Test and inspections		\$	%
Total Process Costs		\$	%
Other manufacturing costs		2019	
		Cost	
Yield losses		\$	%
Non-recurring expenses		\$	%
Documentation and packing		\$	%
Total Other Costs		\$	%
Selling price		2019	
		Cost	
Total Manufacturing Cost		\$	%
Margin		\$	%
Total Selling Price		\$	per board

Electronic Board PCB Cost & Price
(interface of the costing tool **PCB Price+**).

Estimation of the Cost of the Intel 5CSXFC6C6U23A7N

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Die dimensions: 13.3 mm x 13.3 mm = 177.7 mm²
Bonding number: 440 (pad = 100 μm diameter)



Package Opening



Die View

Estimation of the Main blocks: Digital-Analog Power Memory
Estimation of the Technology: 28nm CMOS (40nm gate length)
Estimation of the Wafer fab unit: 1000 (100mm) (1000mm)



Die Markings

BOM Cost – Electronic Board

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[illegible]

There is a total of 100 components on the Main Board. 50 components are on the top side and 50 components are on the bottom side.

The material cost of the Electronic Board is estimated to \$ for **1M** units in 2019.

Manufacturing Cost Breakdown

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Aptiv (Delphi) 4N0.907.107 (Audi A8 zFAS)		ASSEMBLY COST		MATERIAL COST	MANUFACTURING COST <i>without scrap & supplying costs</i>
	Article Qty	ADDED VALUE	Manufacturing Duration (s)		
Housing	1	\$ 1.330	1.330	\$ 1.330	\$ 1.330
Electronic Board	1	\$ 1.440	1.440	\$ 1.440	\$ 1.440
TOTAL		\$ 2.770	2.770	\$ 2.770	\$ 2.770

Aptiv (Delphi) 4N0.907.107 (Audi A8 zFAS)	ASSEMBLY COST	MATERIAL COST	%
Housing	1.330	1.330%	1.330%
Electronic Board	1.440	1.440%	1.440%
TOTAL	%	%	100%

The Total Manufacturing Cost is estimated to \$ 2.770 including \$ 1.440 for Material Cost (52 %) and \$ 1.330 for Added Value Cost (48 %).

- Financial Ratios
- ▶ Manufacturer Price

Estimation of the Manufacturer Price

Year	Annual Quantity	Manufacturing Location	Material Cost	Scrap	Supplying	Total Material Cost	Assembly Cost	Manufacturing Cost	Aptiv (Delphi)			
									R&D	G&A	Profit	Estimated Manufacturer Price
2019	1,000,000	Germany	\$100,000	\$10,000	\$10,000	\$120,000	\$10,000	\$130,000	\$10,000	\$10,000	\$10,000	\$150,000

2019 Manufacturer Price Breakdown



The bill of material (BOM) cost is estimated to \$100,000 for the System.

To this, we must add some scrap costs and component supplying costs to obtain the total material cost of \$120,000.

The assembly cost is estimated to \$10,000, so the manufacturing cost is \$130,000.

With estimated costs of R&D, G&A and Profit, the average manufacturer price of Aptiv (Delphi) can be estimated at \$150,000 when using the estimated economic parameters of Aptiv (Delphi).

Related Reports

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MARKET AND TECHNOLOGY REPORTS - YOLE DÉVELOPPEMENT

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The Audi A8 zFAS ADAS Platform by Aptiv

The first level 3 autonomous driving system, designed by Audi and manufactured by Aptiv (Delphi), integrates high-performance processors from Nvidia (Tegra K1), Altera (Cyclon V), Infineon (Aurix), and Mobileye (EyeQ3 image processor).



Title: The Audi A8 zFAS ADAS Platform by Aptiv

Pages: 87

Date: December 2019

Format:
PDF & Excel file

Price:
EUR 3,990

Today's semi-autonomous cars use a wide range of sensors (i.e. cameras, radar, and LiDAR) to assist the driver. However, the driver must still handle the actual driving. In order to reach the conditional autonomy offered at level 3, it was necessary to bundle sensor-derived data into a central interface unit that can combine and interpret the data, and react without human intervention.

The zFAS control unit, manufactured by Aptiv (Delphi) in Hungary, is the brain of the Audi A8's advanced driver assistance system (ADAS) platform. zFas combines multiple computing tasks on a powerful main board equipped with multiple microprocessors and a microcontroller. The included Nvidia Tegra K1 sensor is dedicated to processing data from the cameras to create a 360-degree surround view of the vehicle. Meanwhile, the Mobileye EyeQ3 processes the more time-critical data from the stereo front-camera and driver-monitoring camera. The Intel (Altera) Cyclone V chip, with an integrated ARM processor, is used for most of the sensor data fusion, and the Infineon Tricore chip

is responsible for steering and braking decisions. Lastly, AT&S supplies the electronic board, which uses semi-Flex technology.

Our report, which is based on a complete teardown analysis of the Audi A8 zFAS control unit, provides the bill-of-materials (BOM) and manufacturing cost of the control unit. The report also includes a resumed physical analysis of the main ICs (NVIDIA, Intel, and Infineon), along with a complete cost analysis and an estimated sales price.

COMPLETE TEARDOWN WITH

- Detailed photos
- Block diagram
- Supply chain
- NVIDIA Tegra K1 (physical analysis summary)
- PCB cross-section
- Die pictures and cost estimates for the main ICs
- Complete, priced bill-of-materials
- Manufacturing process flow
- Manufacturing cost analysis
- Estimated sales price

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Estimated Price Analysis

- Estimated Sales Price

AUTHOR



David Le Gac joined System Plus Consulting as a cost analyst in 2013. He is in charge of reverse costing, with a focus on boards and systems. He previously worked for Lacroix Electronics where he was in charge of its component database. He holds a master's degree in microelectronics from the University of Rennes.

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December 2019 - EUR 3,990*



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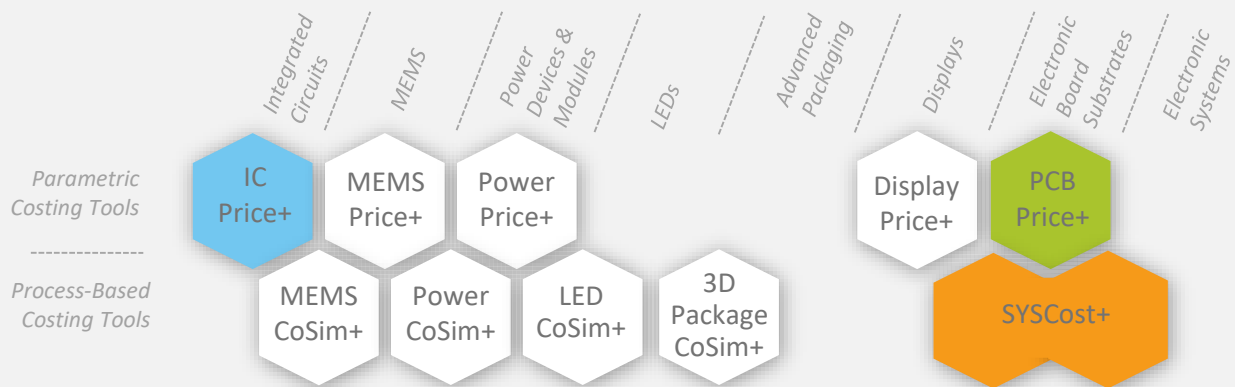


Artificial Intelligence Computing for Automotive 2019

Artificial Intelligence for automotive: why you should care.

February 2019 - EUR 6,490*

COSTING TOOLS



Our analysis is performed with our costing tools SYSCost+, IC Price+ and PCB Price+. System Plus Consulting offers powerful costing tools to evaluate the production cost and selling price from single chip to complex structures.

SYSCost+

Provides all component costs estimation including PCB, housing and connectors, and a simulation of the assembly cost and test process at the board and system level.

IC Price+

Performs the necessary cost simulation of any Integrated Circuit: ASICs, microcontrollers, memories, DSP, smartpower...

PCB Price+

Performs the necessary cost simulation of a large type of PCB substrates according to different technical characteristics such as the material, the metal layers, the type of Vias, etc.

ABOUT SYSTEM PLUS CONSULTING

WHAT IS A REVERSE COSTING®?

Reverse Costing® is the process of disassembling a device (or a system) in order to identify its technology and calculate its manufacturing cost, using in-house models and tools.



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2.1 Products are sent by email to the Buyer:

- within [1] month from the order for Products already released; or

- within a reasonable time for Products ordered prior to their effective release. In this case, the Seller shall use its best endeavours to inform the Buyer of an indicative release date and the evolution of the work in progress.

2.2 Some weeks prior to the release date the Seller can propose a pre-release discount to the Buyer

The Seller shall by no means be responsible for any delay in respect of article 2.2 above, and including incases where a new event or access to new contradictory information would require for the analyst extra time to compute or compare the data in order to enable the Seller to deliver a high quality Products.

2.3 The mailing of the Product will occur only upon payment by the Buyer, in accordance with the conditions contained in article 3.

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2.5 The person receiving the Products on behalf of the Buyer shall immediately verify the quality of the Products and their conformity to the order. Any claim for apparent defects or for non-conformity shall be sent in writing to the Seller within 8 days of receipt of the Products. For this purpose, the Buyer agrees to produce sufficient evidence of such defects.

2.6 No return of Products shall be accepted without prior information to the Seller, even in case of delayed delivery. Any Product returned to the Seller without providing prior information to the Seller as required under article 2.5 shall remain at the Buyer's risk.

3. Price, invoicing and payment

3.1 Prices are given in the orders corresponding to each Product sold on a unit basis or corresponding to annual subscriptions. They are expressed to be inclusive of all taxes. The prices may be reevaluated from time to time. The effective price is deemed to be the one applicable at the time of the order.

3.2 Yole may offer a pre release discount for the companies willing to acquire in the future the specific report and agreeing on the fact that the report may be release later than the anticipated release date. In exchange to this uncertainty, the company will get a discount that can vary from 15% to 10%.

3.3 Payments due by the Buyer shall be sent by cheque payable to Yole Développement, credit card or by electronic transfer to the following account:

HSBC, 1 place de la Bourse 69002 Lyon France

Bank code: 30056

Branch code: 00170

Account n°: 0170 200 1565 87

BIC or SWIFT code: CCFRFRPP

IBAN: FR76 3005 6001 7001 7020 0156 587

To ensure the payments, the Seller reserves the right to request down payments from the Buyer. In this case, the need of down payments will be mentioned on the order.

3.4 Payment is due by the Buyer to the Seller within 30 days from invoice date, except in the case of a particular written agreement. If the Buyer fails to pay within this time and fails to contact the Seller, the latter shall be entitled to invoice interest in arrears based on the annual rate Refi of the «BCE» + 7 points, in accordance with article L. 441-6 of the French Commercial Code. Our publications (report, database, tool...) are delivered only after reception of the payment.

3.5 In the event of termination of the contract, or of misconduct, during the contract, the Seller will have the right to invoice at the stage in progress, and to take legal action for damages.

4. Liabilities

4.1 The Buyer or any other individual or legal person acting on its behalf, being a business user buying the Products for its business activities, shall be solely responsible for choosing the Products and for the use and interpretations he makes of the documents it purchases, of the results he obtains, and of the advice and acts it deduces thereof.

4.2 The Seller shall only be liable for (i) direct and (ii) foreseeable pecuniary loss, caused by the Products or arising from a material breach of this agreement

4.3 In no event shall the Seller be liable for:

a) damages of any kind, including without limitation, incidental or consequential damages (including, but not limited to, damages for loss of profits, business interruption and loss of programs or information) arising out of the use of or inability to use the Seller's website or the Products, or any information provided on the website, or in the Products;

b) any claim attributable to errors, omissions or other inaccuracies in the Product or interpretations thereof.

4.4 All the information contained in the Products has been obtained from sources believed to be reliable. The Seller does not warrant the accuracy, completeness adequacy or reliability of such information, which cannot be guaranteed to be free from errors.

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4.6 In the case where, after inspection, it is acknowledged that the Products contain defects, the Seller undertakes to replace the defective products as far as the supplies allow and without indemnities or compensation of any kind for labor costs, delays, loss caused or any other reason. The replacement is guaranteed for a maximum of two months starting from the delivery date. Any replacement is excluded for any event as set out in article 5 below.

4.7 The deadlines that the Seller is asked to state for the mailing of the Products are given for information only and are not guaranteed. If such deadlines are not met, it shall not lead to any damages or cancellation of the orders, except for non acceptable delays exceeding [4] months from the stated deadline, without information from the Seller. In such case only, the Buyer shall be entitled to ask for a reimbursement of its first down payment to the exclusion of any further damages.

4.8 The Seller does not make any warranties, express or implied, including, without limitation, those of sale ability and fitness for a particular purpose, with respect to the Products. Although the Seller shall take reasonable steps to screen Products for infection of viruses, worms, Trojan horses or other codes containing contaminating or destructive properties before making the Products available, the Seller cannot guarantee that any Product will be free from infection.

5. Force majeure

The Seller shall not be liable for any delay in performance directly or indirectly caused by or resulting from acts of nature, fire, flood, accident, riot, war, government intervention, embargoes, strikes, labor difficulties, equipment failure, late deliveries by suppliers or other difficulties which are beyond the control, and not the fault of the Seller.

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6.1 All the IPR attached to the Products are and remain the property of the Seller and are protected under French and international copyright law and conventions.

6.2 The Buyer agreed not to disclose, copy, reproduce, redistribute, resell or publish the Product, or any part of it to any other party other than employees of its company. The Buyer shall have the right to use the Products solely for its own internal information purposes. In particular, the Buyer shall therefore not use the Product for purposes such as:

- Information storage and retrieval systems;
- Recordings and re-transmittals over any network (including any local area network);
- Use in any timesharing, service bureau, bulletin board or similar arrangement or public display;
- Posting any Product to any other online service (including bulletin boards or the Internet);
- Licensing, leasing, selling, offering for sale or assigning the Product.

6.3 The Buyer shall be solely responsible towards the Seller of all infringements of this obligation, whether this infringement comes from its employees or any person to whom the Buyer has sent the Products and shall personally take care of any related proceedings, and the Buyer shall bear related financial consequences in their entirety.

6.4 The Buyer shall define within its company point of contact for the needs of the contract. This person will be the recipient of each new report in PDF format. This person shall also be responsible for respect of the copyrights and will guaranty that the Products are not disseminated out of the company.

6.5 In the context of annual subscriptions, the person of contact shall decide who within the Buyer, shall be entitled to access on line the reports on I-micronews.com. In this respect, the Seller will give the Buyer a maximum of 10 password, unless the multiple sites organization of the Buyer requires more passwords. The Seller reserves the right to check from time to time the correct use of this password.

6.6 In the case of a multisite, multi license, only the employee of the buyer can access the report or the employee of the companies in which the buyer have 100% shares. As a matter of fact the investor of a company, the joint venture done with a third party etc...cannot access the report and should pay a full license price.

7. Termination

7.1 If the Buyer cancels the order in whole or in part or postpones the date of mailing, the Buyer shall indemnify the Seller for the entire costs that have been incurred as at the date of notification by the Buyer of such delay or cancellation. This may also apply for any other direct or indirect consequential loss that may be borne by the Seller, following this decision.

7.2 In the event of breach by one Party under these conditions or the order, the non-breaching Party may send a notification to the other by recorded delivery letter upon which, after a period of thirty (30) days without solving the problem, the non-breaching Party shall be entitled to terminate all the pending orders, without being liable for any compensation.

8. Miscellaneous

All the provisions of these Terms and Conditions are for the benefit of the Seller itself, but also for its licensors, employees and agents. Each of them is entitled to assert and enforce those provisions against the Buyer.

Any notices under these Terms and Conditions shall be given in writing. They shall be effective upon receipt by the other Party.

The Seller may, from time to time, update these Terms and Conditions and the Buyer, is deemed to have accepted the latest version of these terms and conditions, provided they have been communicated to him in due time.

9. Governing law and jurisdiction

9.1 Any dispute arising out or linked to these Terms and Conditions or to any contract (orders) entered into in application of these Terms and Conditions shall be settled by the French Commercial Courts of Lyon, which shall have exclusive jurisdiction upon such issues.

9.2 French law shall govern the relation between the Buyer and the Seller, in accordance with these Terms and Conditions.



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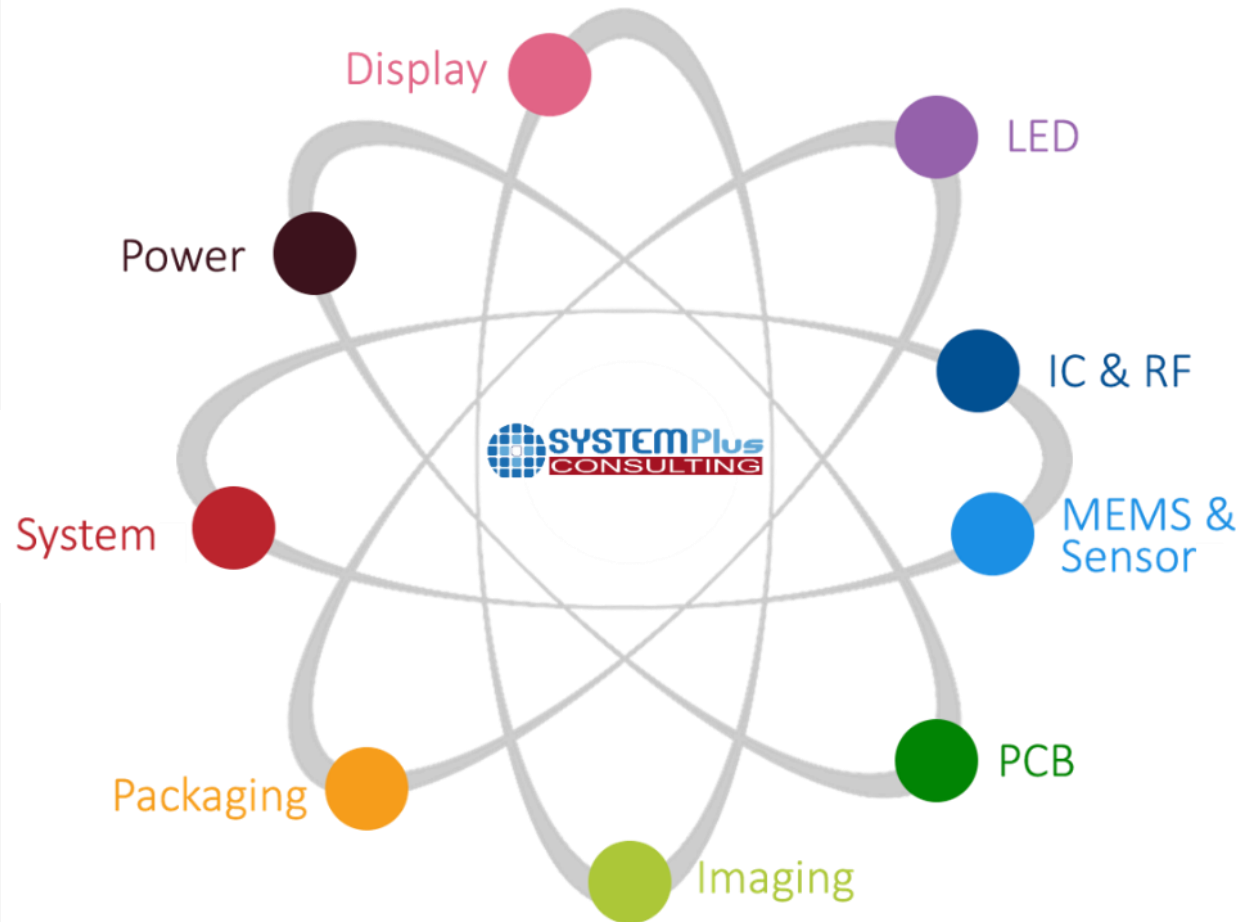
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